

## AMENDMENTS TO THE CLAIMS

1. (Currently amended) A method for forming a solder resist pattern comprising the steps of:

pre-treating both sides of a double-sided printed circuit board, wherein pre-treating includes scrubbing;

laminating a semi-cured thermosetting film on the both sides of the printed circuit board;  
and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film, the solder resist mask pattern having been previously designed prior to irradiating.

2. (Canceled)

3. (Original) The method for forming a solder resist pattern according to claim 1, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

4. (Previously presented) A method for forming a solder resist pattern comprising the steps of:

pre-treating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated by buildup process;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film.

5. (Original) The method for forming a solder resist pattern according to claim 4, wherein the pretreatment includes scrubbing.

6. (Previously presented) The method for forming a solder resist pattern according to claim 5, further comprising curing the thermosetting film after laminating the thermosetting film.

7. (Previously presented) A method for forming a solder resist pattern comprising the steps of:

pre-treating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated in a parallel manner;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film.

8. (Original) The method for forming a solder resist pattern according to claim 7, wherein the pre-treatment includes scrubbing.

9. (Previously presented) The method for forming a solder resist pattern according to claim 8, further comprising curing the thermosetting film after laminating the thermosetting film.

10. (Previously presented) The method of claim 1, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

11. (Previously presented) The method of claim 4, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

12. (Previously presented) The method of claim 7, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

13. (Previously presented) A method for forming a solder resist pattern, comprising:

pre-treating both sides of a double-sided printed circuit board to provide pre-treated sides of a printed circuit board;

applying a semi-cured thermosetting film on the pre-treated sides of the printed circuit board to provide a thermoset film on the printed circuit board; and

irradiating a laser beam on the thermoset film to selectively remove the thermoset film to provide a solder resist pattern.

14. (Previously presented) The method of claim 13, wherein pre-treating includes scrubbing.

15. (Previously presented) The method of claim 13, further comprising curing the thermosetting film.

16. (Previously presented) A method for forming a solder resist pattern comprising:  
pre-treating a portion exposed from a plurality of layers, constituting a multi-layer printed circuit board fabricated by a buildup process to provide a pre-treated portion;

laminating a thermosetting film on the pre-treated portion to provide a thermoset film;  
and

irradiating a laser beam on the thermoset film to selectively remove the film to provide a solder resist pattern.

17. (Previously presented) The method of claim 16, wherein pre-treating includes scrubbing.

18. (Previously presented) the method of claim 16, further comprising curing the thermosetting film.

19. (Previously presented) A method for forming a solder resist pattern, comprising:

pre-treating a portion exposed from a plurality of layers constituting a multi-layer printed circuit board fabricated in a parallel manner to provide a pre-treated portion;

laminating a thermosetting film on the pre-treated portion to provide a thermoset film;  
and

irradiating a laser beam on the thermoset film to selectively remove the thermoset film to provide a solder resist pattern.

20. (Previously presented) The method of claim 19, wherein pre-treating includes scrubbing.

21. (Previously presented) The method of claim 19, further comprising curing the thermosetting film.